1. Part Number: **LBF6232-30DLXA-A**

2. Structure: The LED light bar mounted LED dice (bare chip) on substrate by array (3serial 2parallel 2color)

3. Application: Lighting source

4. Maximum Condition (Ta＝25℃)

Item	Symbol	Condition	Unit
Admissibility disipation ※1	Po	4.32	W
Forward Current ※1	I_F	0.4	A
Operation Temperature	T_{op}	-30～+85	℃
Preservation Temperature	T_{stg}	-40～+100	℃
Junction Temperature	Tj	125	℃

※1：one color (D;6500K / L;2700K)

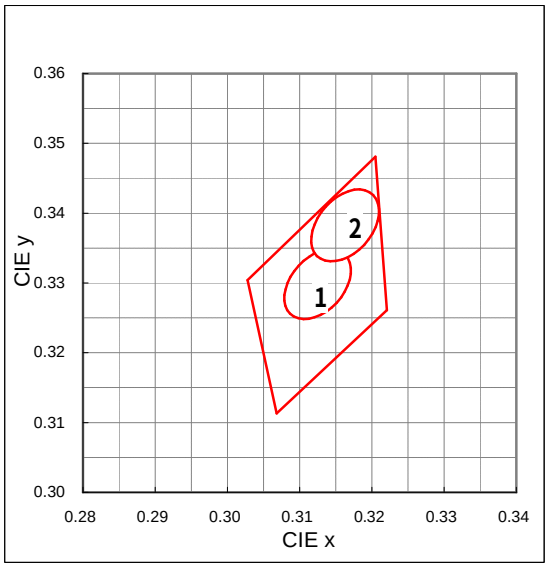
5. Electrical and optical Characteristics (Ta＝25℃)

Item	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage ※2	V_F	7.95	8.70	9.45	V	I_F= 150 mA
Luminous Flux (D) ※3	Φ_v	171.4	176.8	-	lm	I_F= 150 mA
Luminous Flux (L) ※3	Φ_v	146.6	151.2	-	lm	I_F= 150 mA
Color Temperature (D)	T_{cp}	6025	6406	6787	K	I_F= 150 mA
Color Temperature (L)	T_{cp}	2613	2739	286	K	I_F= 150 mA
Deviation Color (D)	duv	+0.0009	+0.0048	+0.0086	-	I_F= 150 mA
Deviation Color (L)	duv	-0.0034	+0.0004	+0.0041	-	I_F= 150 mA
General Color Rendering Index	Ra	75	80	-	-	I_F= 150 mA

※1：measurement tolerance：± 3 %
※2：measurement tolerance：± 7 %
※These data are measured by a measuring equipment complying with CIE125 Condition B.

6. Chromaticity coordinate （Ta＝25℃、IF＝150mA、measurement tolerance：±0.005）

① D ; 6500K



Chromaticity coordinates Point

6500K-2	
x	y
0.3163	0.3382

6500K-1	
x	y
0.3125	0.3298

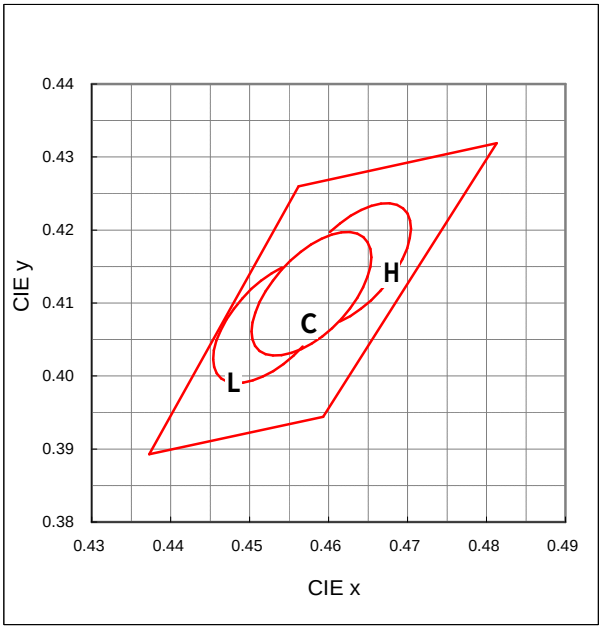
※MacAdam ellipse 3step

ANSI C78.377 standard

LBF62*	
6500K	
x	y
0.3068	0.3113
0.3221	0.3261
0.3205	0.3481
0.3028	0.3304
center point (0.3123,0.3282)	

<Range within 1Bar>
x : R≦0.015
y : R≦0.020
(R=max-min)

② L ; 2700K



Chromaticity coordinates Point

2700K-H	
x	y
0.4628	0.4150

2700K-C	
x	y
0.45785	0.41115

2700K-L	
x	y
0.4529	0.4073

※MacAdam ellipse 4step

ANSI C78.377 standard

LBF62*	
2700K	
x	y
0.4373	0.3893
0.4593	0.3944
0.4813	0.4319
0.4562	0.4260
center point (0.4578,0.4101)	

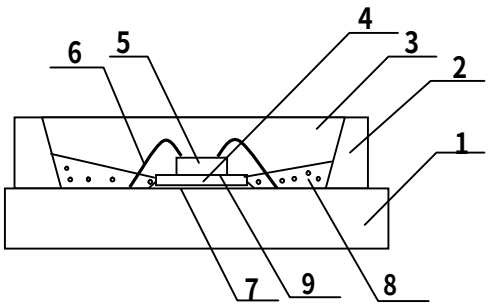
<Range within 1Bar>
x : R≦0.015
y : R≦0.020
(R=max-min)

The product that is located in the square A except for the area of the MacAdam ellipses is to be discussed for sales.

※Color rank

color rank		2700K		
		L	C	H
6500K	1	L1	C1	H1
	2	L2	C2	H2

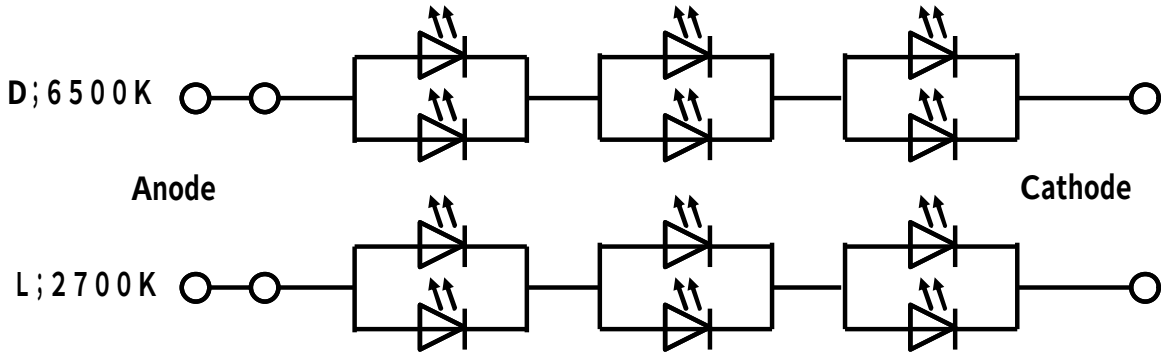
7. Structure



No	Parts Name	Material
1	Substrate	CEM-3 Substrate
2	White Resin	Silicone Resin
3	Resin	Silicone Resin
4	Sub Mount Substrate	Si
5	LED Die	InGaN on Sapphire
6	Bonding Wire	Au
7	Die Bond	Ag
8	White Resin	Silicone Resin (TiO_2)
9	Die Bond	Silicone Resin

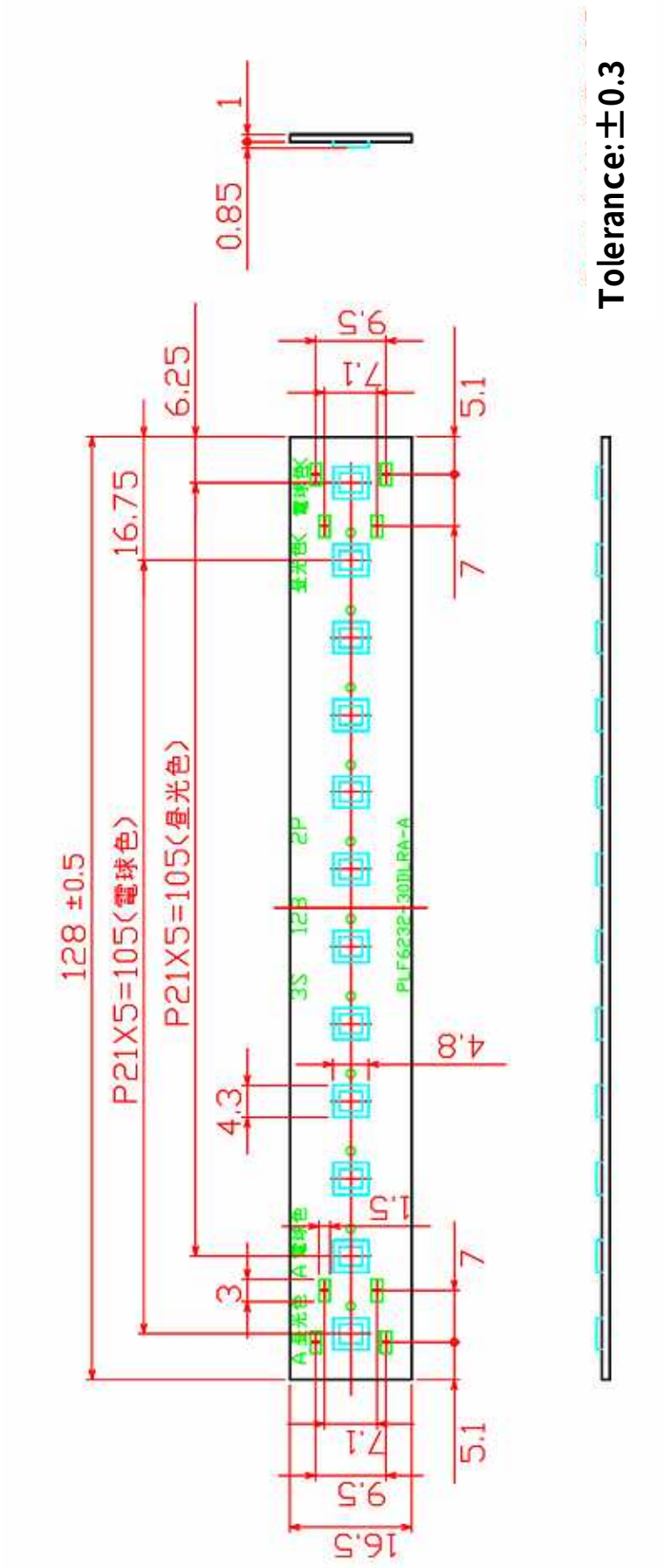
8. Circuit Diagram

3 serial 2 parallel

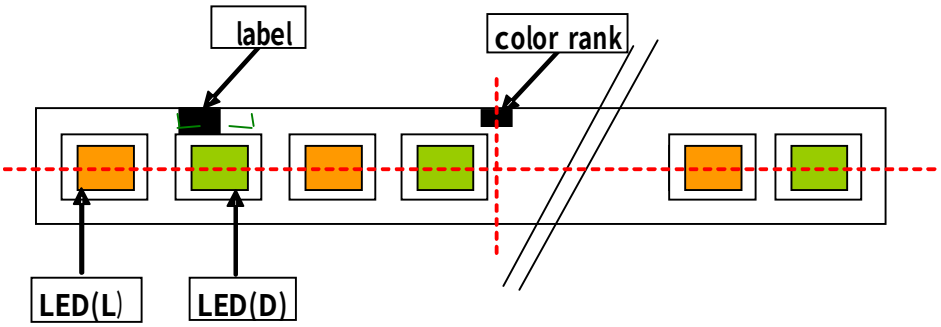


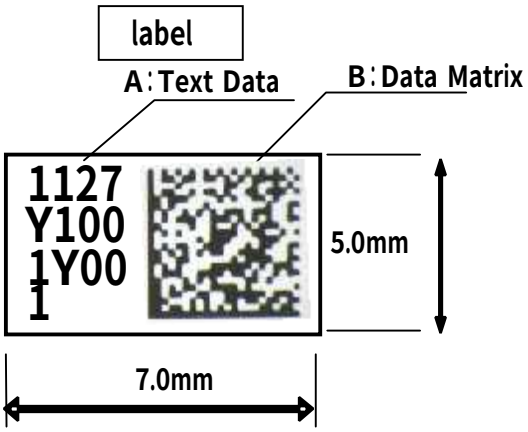
9. Dimension

(Unit: mm)

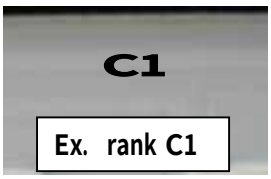


10.Product Label

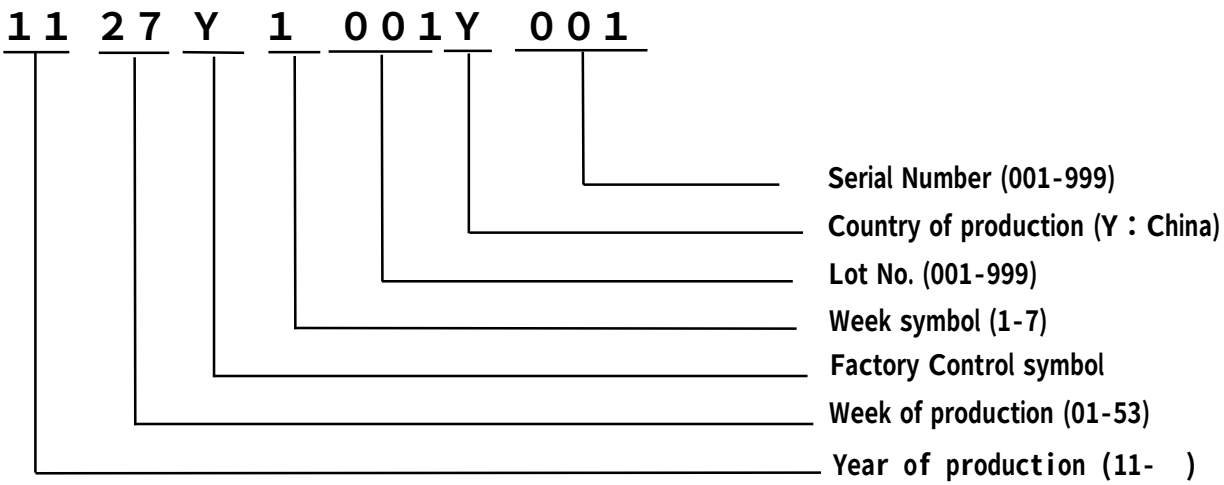




Color rank (L1,L2,C1,C2,H1,H2)



[A] Text Data



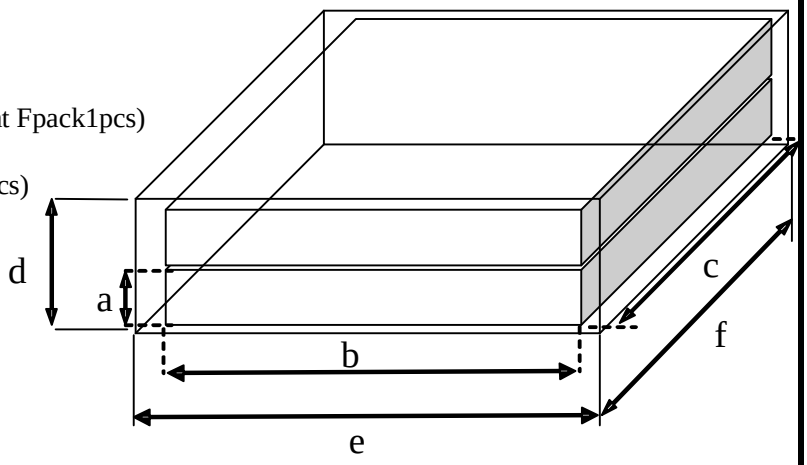
[B] Data Matrix

LBF6232−30DLXA−A	(16grids)	Part Number
1127Y1001Y001	(13grids)	Lot Number
12345678	(8grids)	Factory Control Part

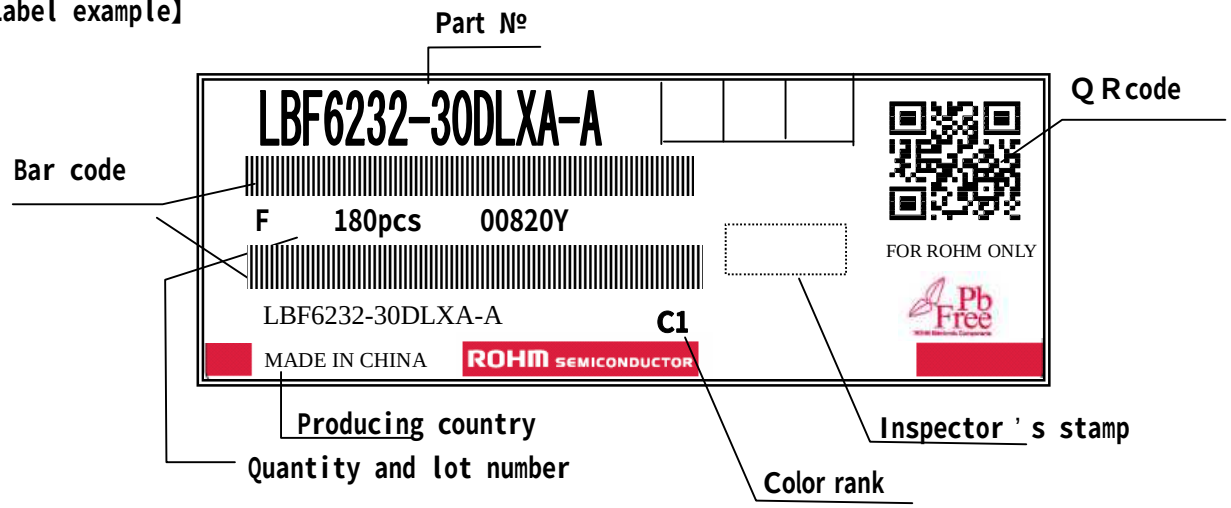
11. Packing

【Package】

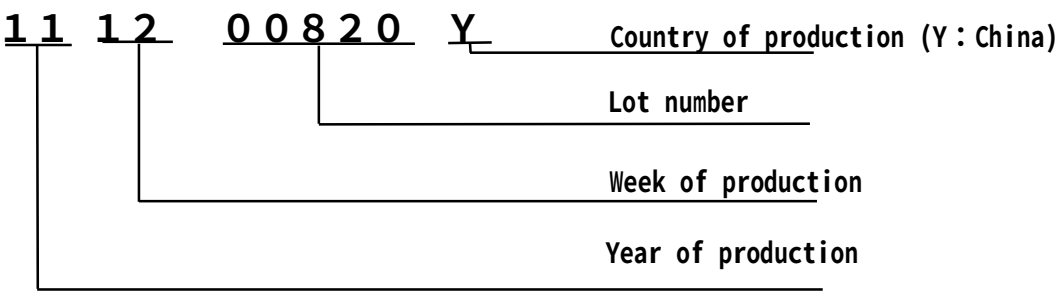
(1) 18 Bars are on one film tray.
(2) Inner package size (Fpack10pcs+vacant Fpack1pcs)
(a)60 x (b)300 x (c)343 (Unit: mm)
(3) Outer package size(inner package×2pcs)
(d)155 x (e)313 x (f)353 (Unit: mm)



【Label example】



【Lot number example】



【Manufacturing factory (country of origin)】

・ROHM SEMICONDUCTOR CHINA CO.,LTD. (China)